

## Photo DMOS-FET Relay

### Description

The **LT236** is a miniature 1-Form A solid state relay in a 4 pin SOP package that employs optically coupled MOSFET technology to provide 1500V of input to output isolation. The optically coupled input is controlled by a highly efficient GaAlAs infrared LED and MOS FETs on the output side.

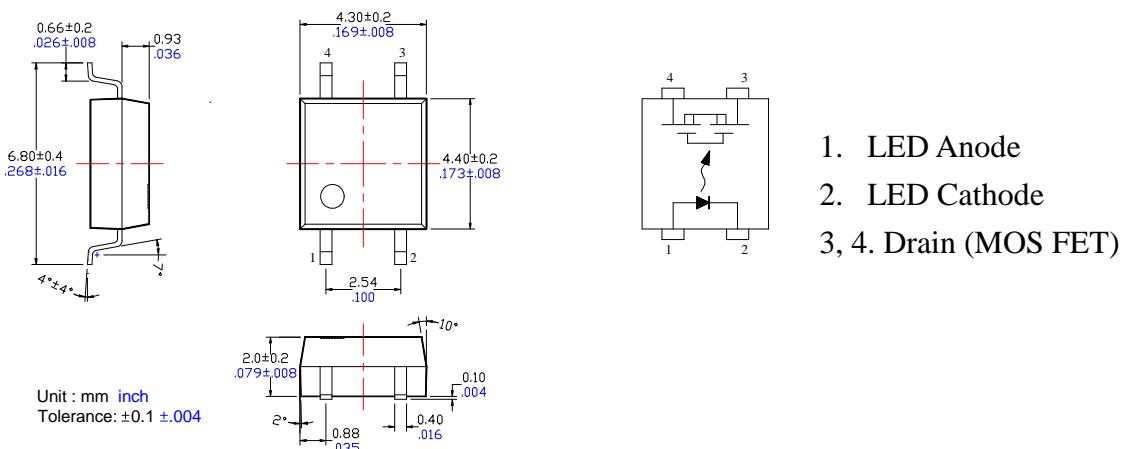
### Features

- SOP package 4 Pin type in miniature design (4.4×4.3×2.0mm / .173×.169×.083inch)
- Low driver power requirements (TTL/CMOS Compatible)
- Low CxR . Output capacitance=22pF(Typ.)
- No moving parts
- High reliability
- Arc-Free with no snubbing circuits
- 1500Vrms Input/Output isolation
- Tape & Reel version available

### Applications

- Telecommunications (PC, Electronic notepad)
- Measuring and Testing equipment
- Industrial control
- Security equipments
- High speed inspection machine

### Outline Dimensions



**Photo DMOS-FET Relay Specifications****Part Name: LT236**

(Load voltage: 100V / Load current: 400mA)

**Absolute Maximum Ratings (Ambient Temperature: 25°C)**

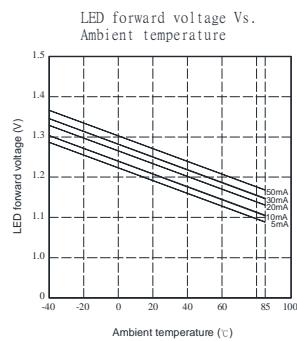
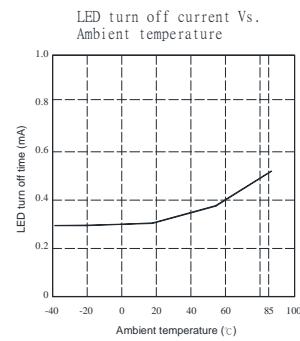
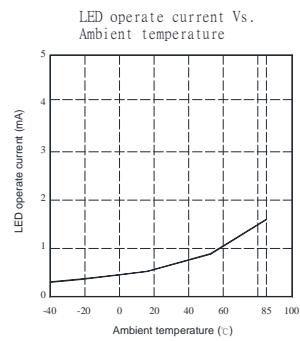
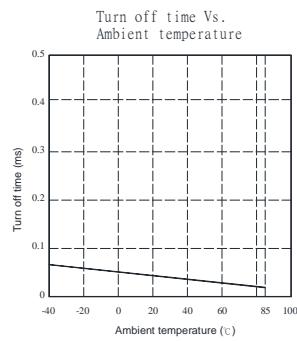
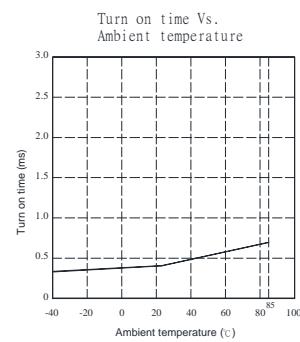
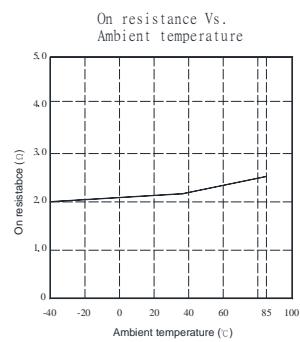
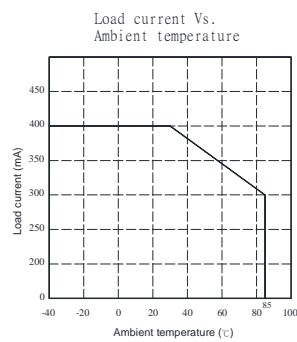
| Item                      |                          | Symbol            | Value       | Units            | Note                |
|---------------------------|--------------------------|-------------------|-------------|------------------|---------------------|
| Input                     | Continuous LED Current   | I <sub>F</sub>    | 50          | mA               |                     |
|                           | Peak LED Current         | I <sub>FP</sub>   | 1000        | mA               | f=100Hz,<br>duty=1% |
|                           | LED Reverse Voltage      | V <sub>R</sub>    | 5           | V                |                     |
|                           | Input Power Dissipation  | P <sub>In</sub>   | 75          | mW               |                     |
| Output                    | Load Voltage             | V <sub>L</sub>    | 100         | V(AC peak or DC) |                     |
|                           | Load Current             | I <sub>L</sub>    | 400         | mA               |                     |
|                           | Peak Load Current        | I <sub>Peak</sub> | 1.0         | A                | 100ms(1 pulse)      |
|                           | Output Power Dissipation | P <sub>out</sub>  | 450         | mW               |                     |
| Total Power Dissipation   |                          | P <sub>T</sub>    | 500         | mW               |                     |
| I/O Breakdown Voltage     |                          | V <sub>I/O</sub>  | 1500        | Vrms             | RH=60%, 1min        |
| Operating Temperature     |                          | T <sub>opr</sub>  | -40 to +85  | °C               |                     |
| Storage Temperature       |                          | T <sub>stg</sub>  | -40 to +100 | °C               |                     |
| Pin Soldering Temperature |                          | T <sub>sol</sub>  | 260         | °C               | 10 sec max.         |

**Electrical Specifications (Ambient Temperature: 25°C)**

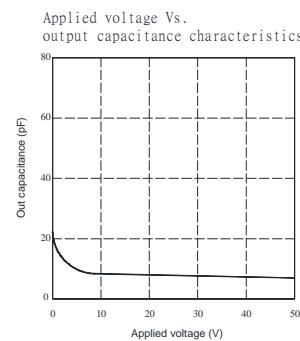
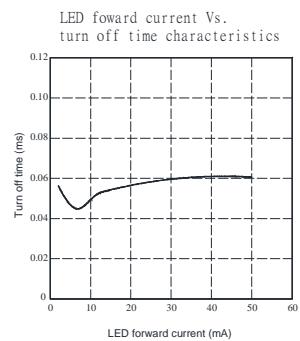
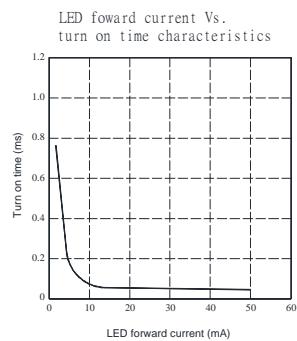
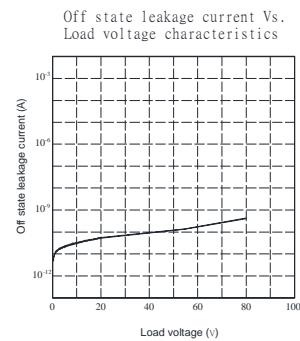
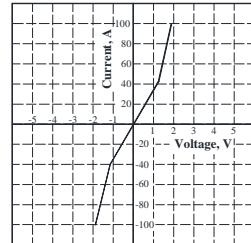
| Item         |                           | Symbol             | MIN.             | TYP. | MAX. | Units | Conditions                                                                      |
|--------------|---------------------------|--------------------|------------------|------|------|-------|---------------------------------------------------------------------------------|
| Input        | LED Forward Voltage       | V <sub>F</sub>     |                  | 1.2  | 1.4  | V     | I <sub>F</sub> =10mA                                                            |
|              | Operation LED Current     | I <sub>F on</sub>  |                  | 0.5  | 2.0  | mA    |                                                                                 |
|              | Recovery LED Current      | I <sub>F off</sub> |                  | 0.35 | 3.0  | mA    |                                                                                 |
|              | Recovery LED Voltage      | V <sub>F off</sub> | 0.7              |      |      | V     |                                                                                 |
| Output       | On-Resistance             | R <sub>on</sub>    |                  | 2.0  | 2.5  | Ω     | I <sub>F</sub> =5mA, I <sub>L</sub> =100mA,<br>Time to flow is within<br>1 sec. |
|              | Off-State Leakage Current | I <sub>Leak</sub>  |                  |      | 1.0  | uA    | V <sub>L</sub> =Rating                                                          |
|              | Output Capacitance        | C <sub>out</sub>   |                  | 22   |      | pF    | V <sub>L</sub> =0, f=1MHz                                                       |
| Transmission | Turn-On Time              | T <sub>on</sub>    |                  | 0.3  | 0.6  | ms    | I <sub>F</sub> =5mA, I <sub>L</sub> =100mA,                                     |
|              | Turn-Off Time             | T <sub>off</sub>   |                  | 0.05 | 0.1  | ms    |                                                                                 |
| Coupled      | I/O Isolation Resistance  | R <sub>I/O</sub>   | 10 <sup>10</sup> |      |      | Ω     | DC500V                                                                          |
|              | I/O Capacitance           | C <sub>I/O</sub>   |                  | 0.8  | 1.5  | pF    | f=1MHz                                                                          |



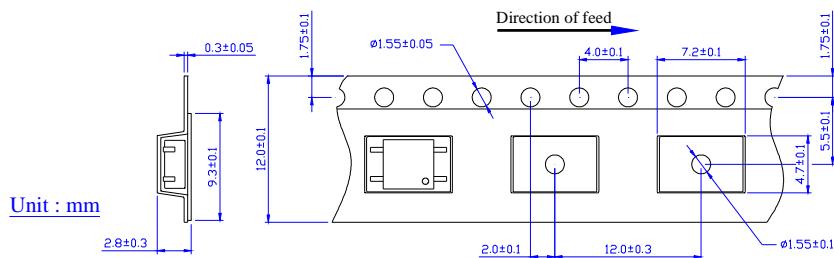
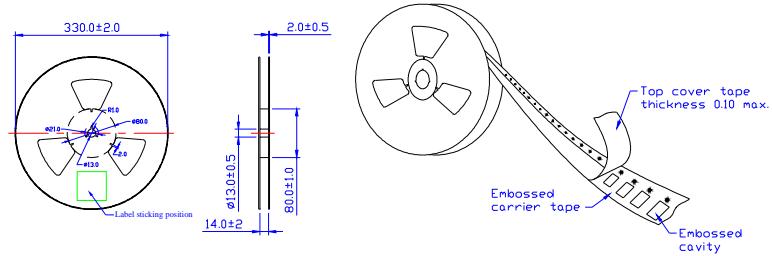
## Reference Data



Voltage Vs. current characteristics  
of output at MOS portion

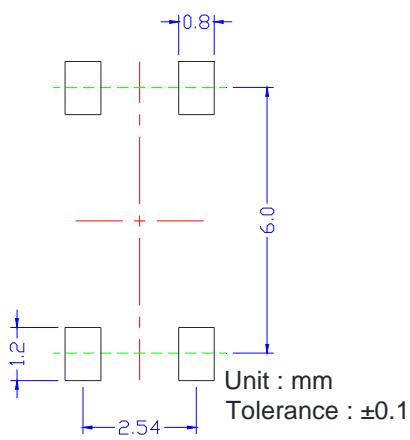


## Taping Specifications for Surface Mount Devices



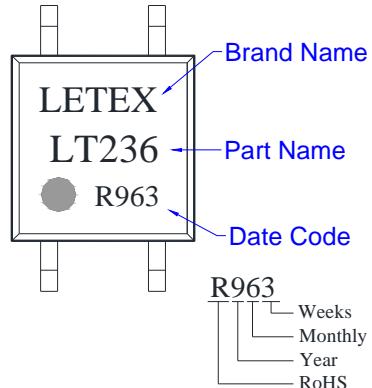
### **Recommended Mounting Pad**

(Top view)



### **Marking**

(Each photo MOS Relay shall be marked with the following information)



- Note:
1. There shall be leader of 230 mm minimum which may consist of carrier and or cover tape follower by a minimum of 160 mm of carrier tape sealed with cover tape.
  2. There shall be a minimum of 160 mm of empty component pockets sealed with cover tape.
  3. Devices are pockets in accordance with EIA standard EIA-481-A and specifications given above.
  4. Packaging: 2,000pcs per reel, 2 reel per box, 5 boxes per carton.